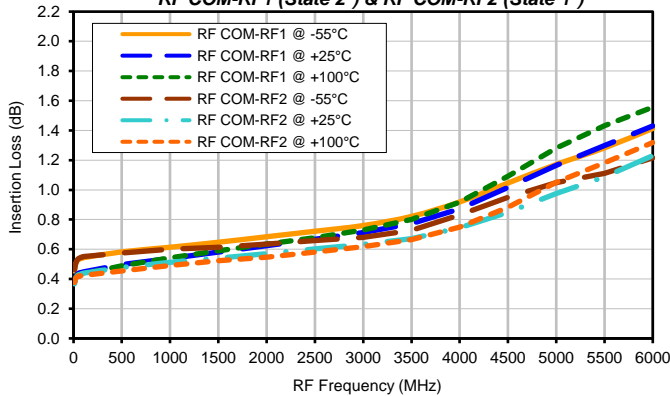
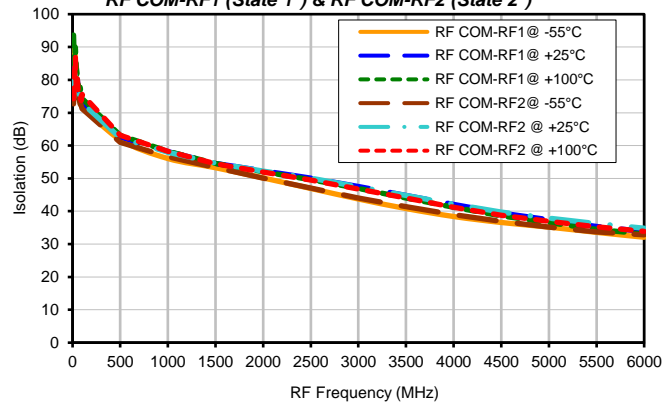


Typical Performance Curves

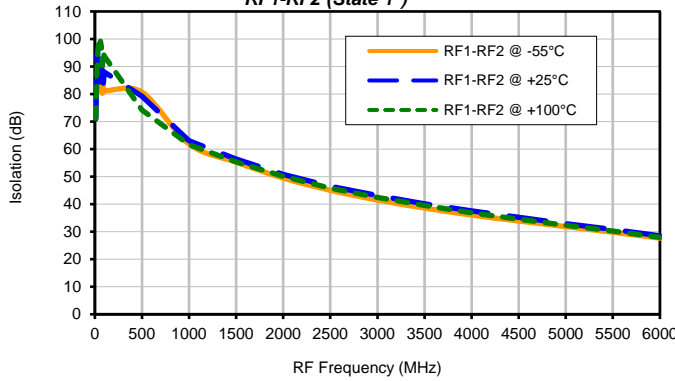
Insertion Loss @ VDD=+4.75V, VEE=-4.75V over Temperature
RF COM-RF1 (State 2*) & RF COM-RF2 (State 1*)



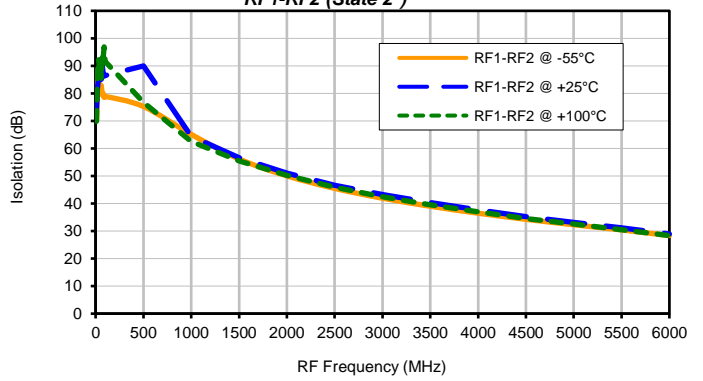
Isolation @ VDD=+4.75V, VEE=-4.75V over Temperature
RF COM-RF1 (State 1*) & RF COM-RF2 (State 2*)



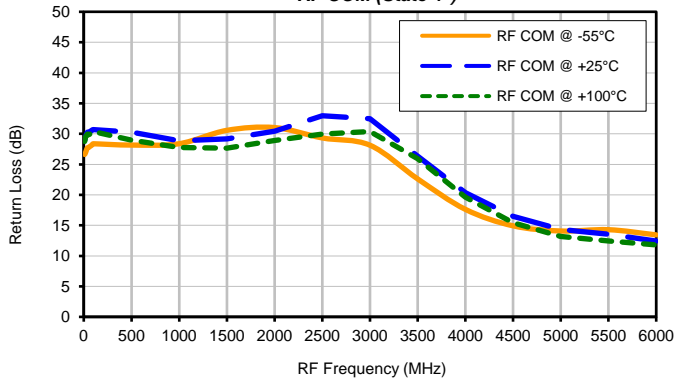
Isolation @ VDD=+4.75V, VEE=-4.75V over Temperature
RF1-RF2 (State 1*)



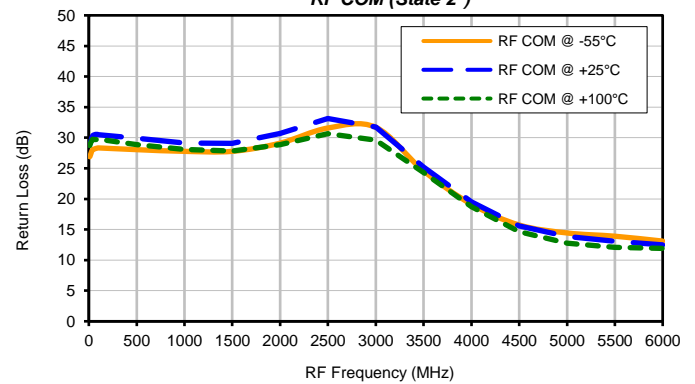
Isolation @ VDD=+4.75V, VEE=-4.75V over Temperature
RF1-RF2 (State 2*)



RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF COM (State 1*)



RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF COM (State 2*)



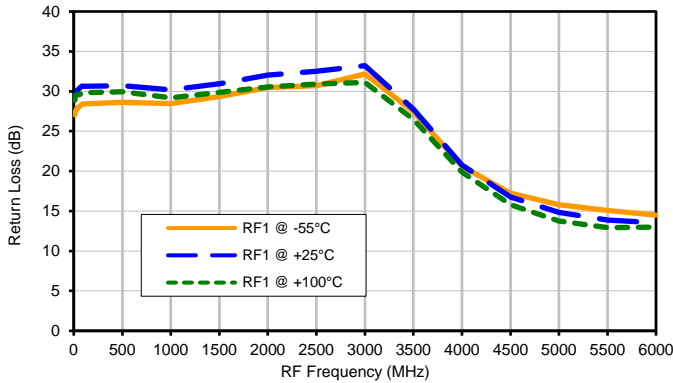
*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

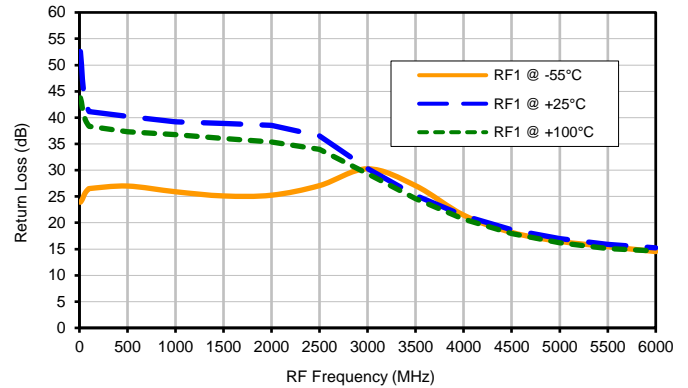
Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package

Typical Performance Curves

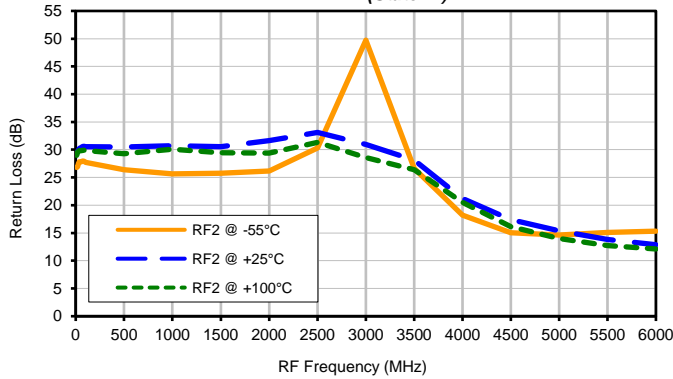
RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF1 (State 2*)



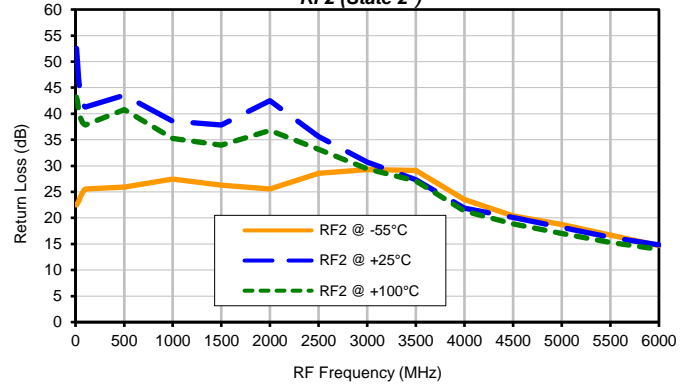
RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF1 (State 1*)



RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF2 (State 1*)



RL @ VDD=+4.75V, VEE=-4.75V over Temperature
RF2 (State 2*)



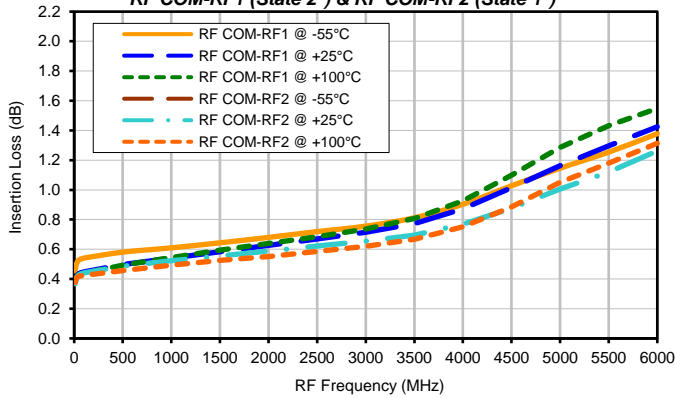
*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

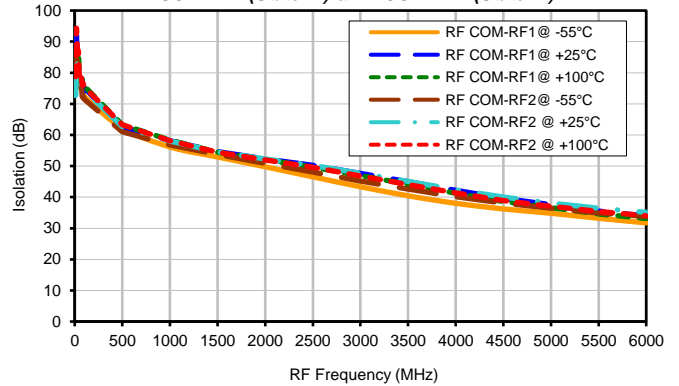
Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package

Typical Performance Curves

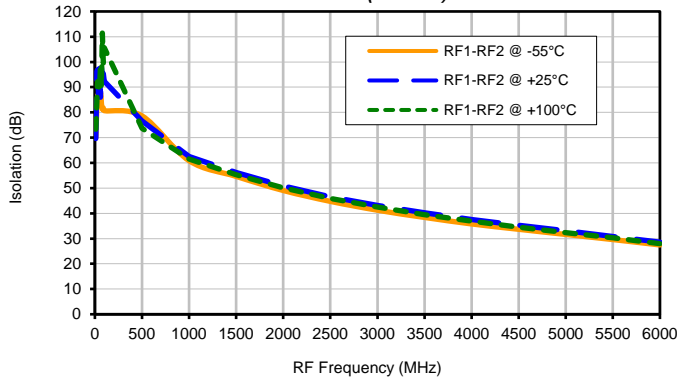
Insertion Loss @ VDD=+5V, VEE =-5V over Temperature
RF COM-RF1 (State 2*) & RF COM-RF2 (State 1*)



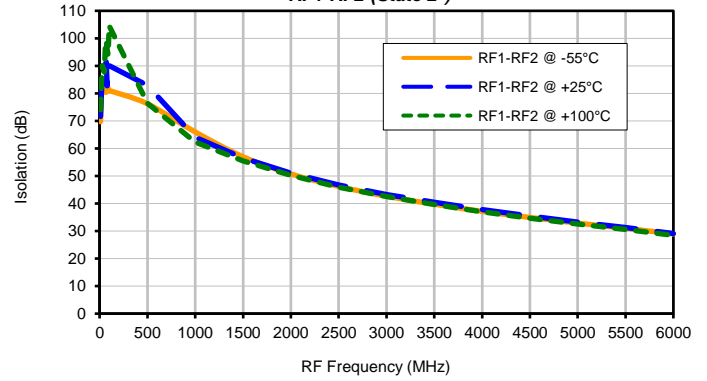
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF COM-RF1 (State 1*) & RF COM-RF2 (State 2*)



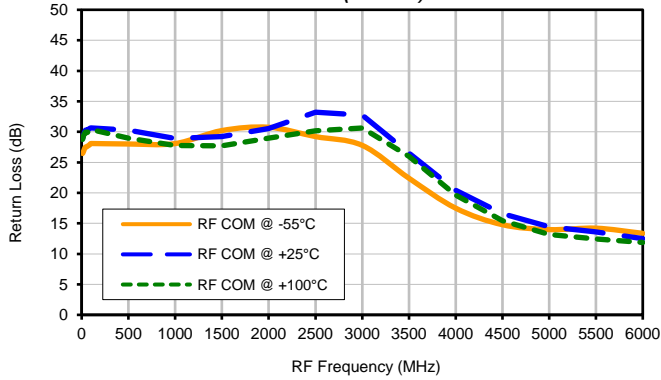
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF1-RF2 (State 1*)



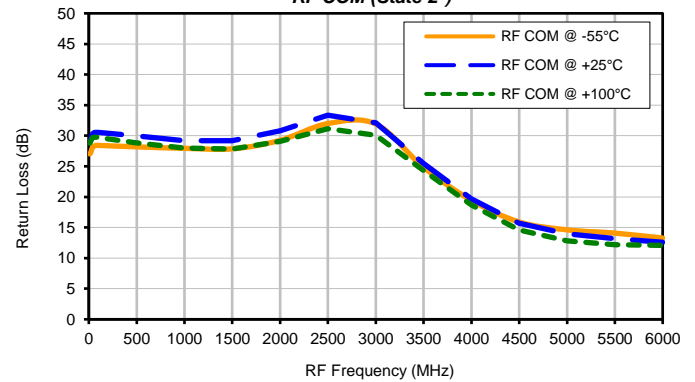
Isolation @ VDD=+5V, VEE =-5V over Temperature
RF1-RF2 (State 2*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF COM (State 1*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF COM (State 2*)



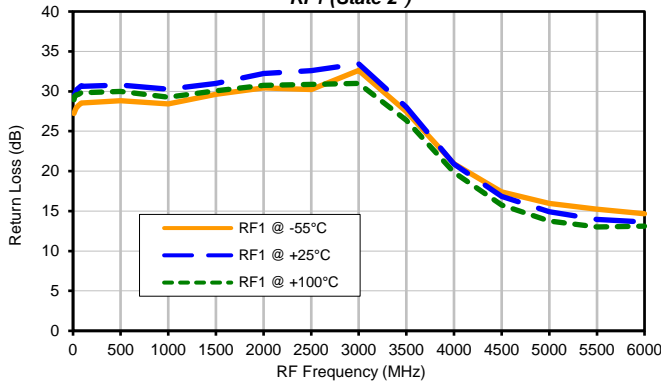
*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

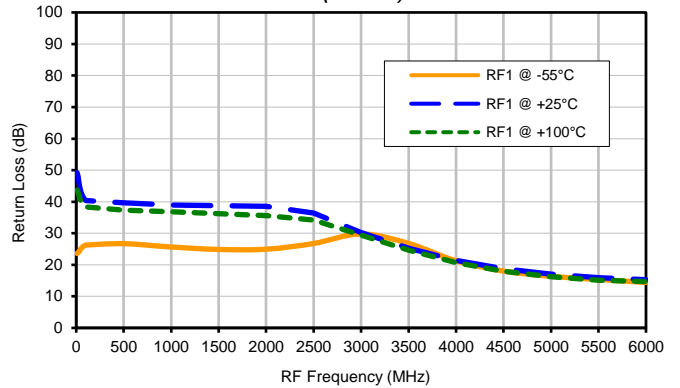
Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package

Typical Performance Curves

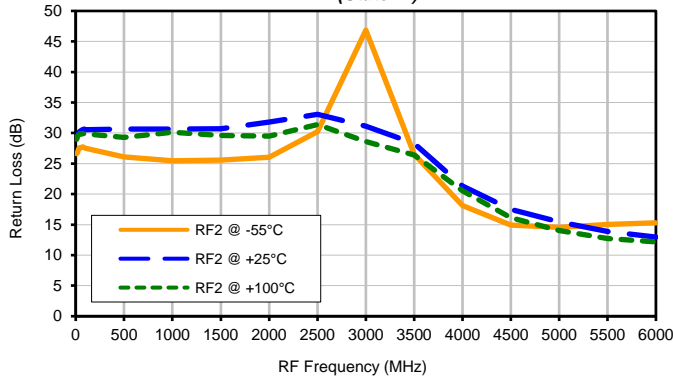
RL @ VDD=+5V, VEE =-5V over Temperature
RF1 (State 2*)



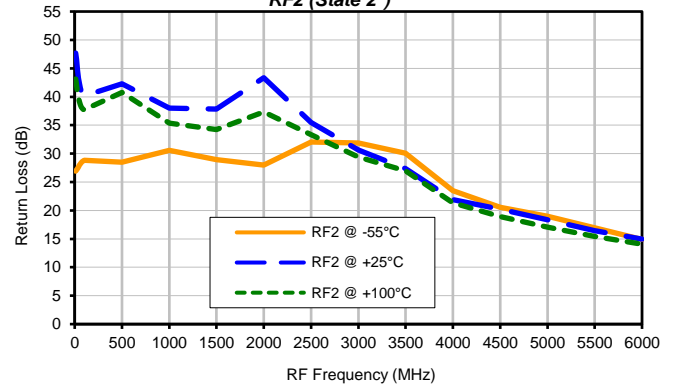
RL @ VDD=+5V, VEE =-5V over Temperature
RF1 (State 1*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF2 (State 1*)



RL @ VDD=+5V, VEE =-5V over Temperature
RF2 (State 2*)

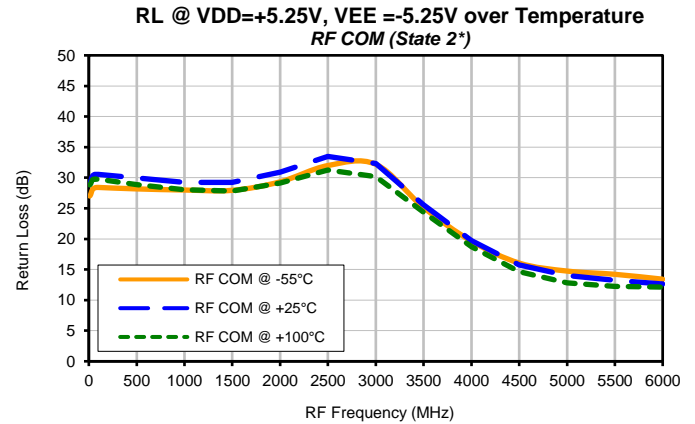
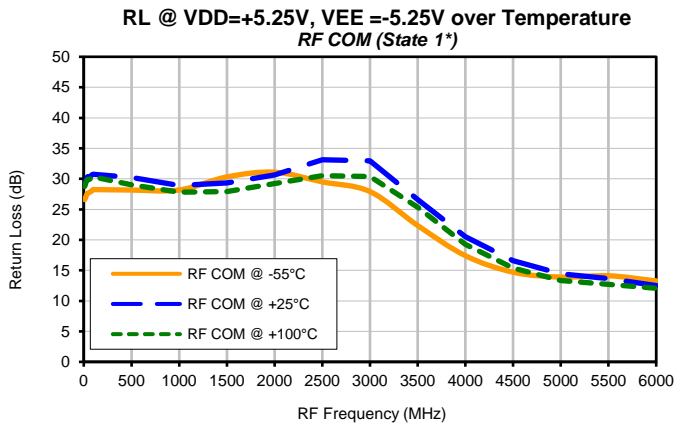
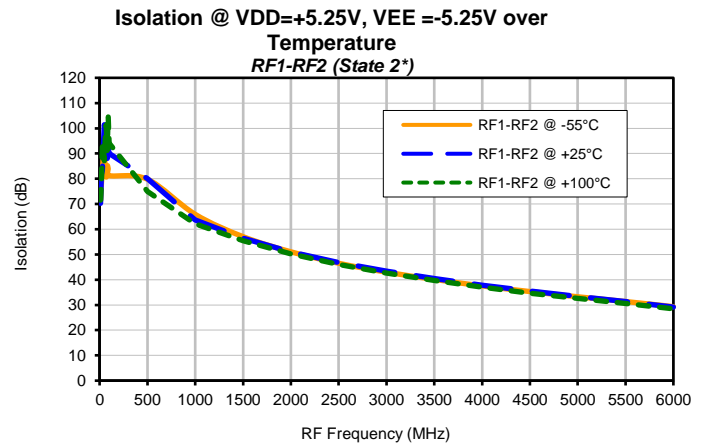
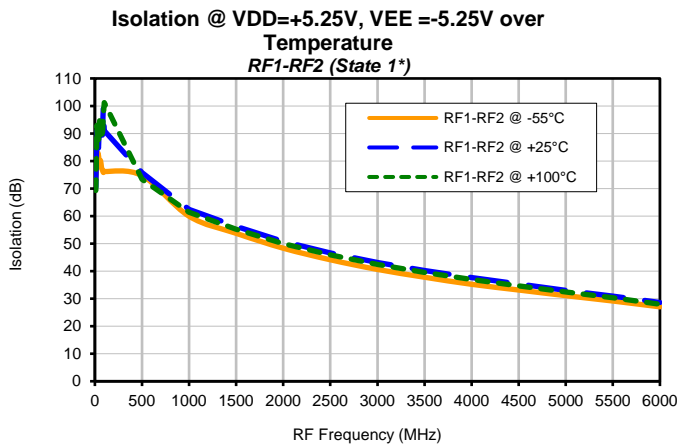
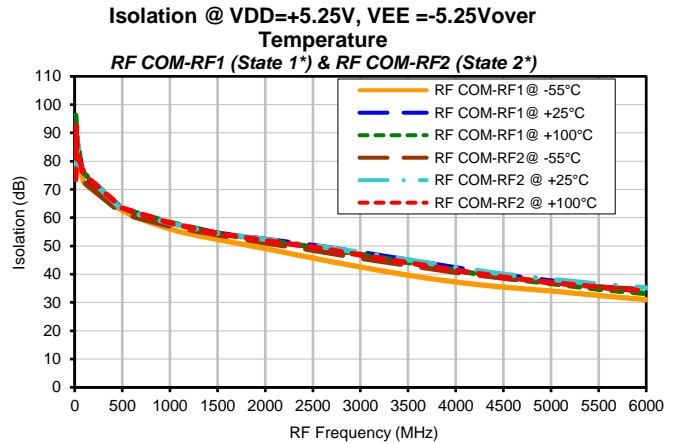
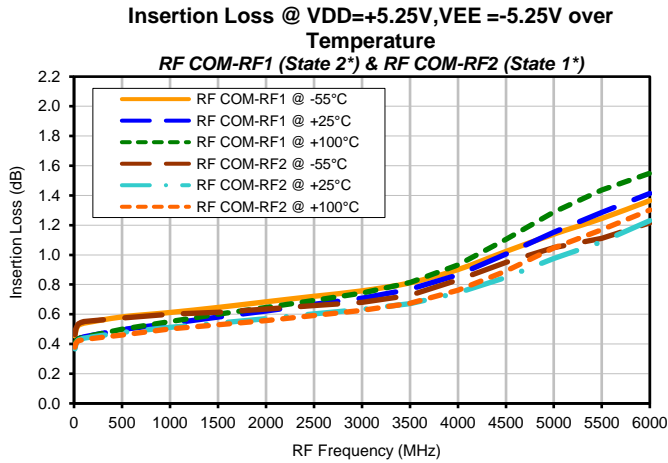


*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package

Typical Performance Curves



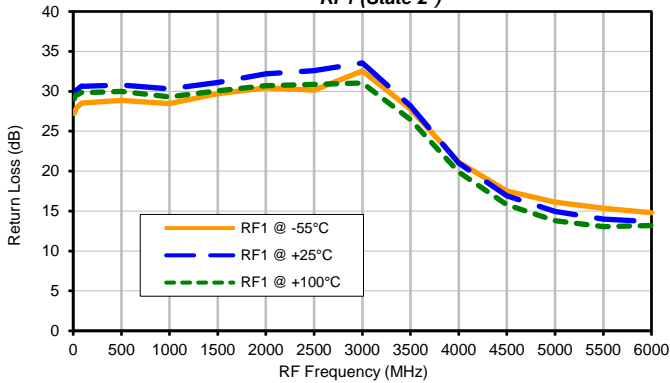
*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

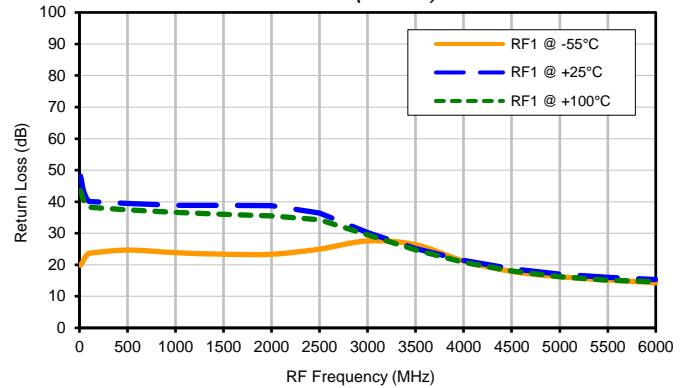
Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package

Typical Performance Curves

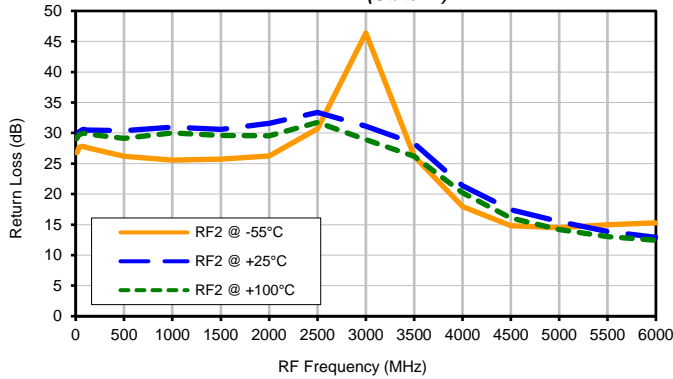
RL @ VDD=+5.25V, VEE =-5.25V over Temperature
RF1 (State 2*)



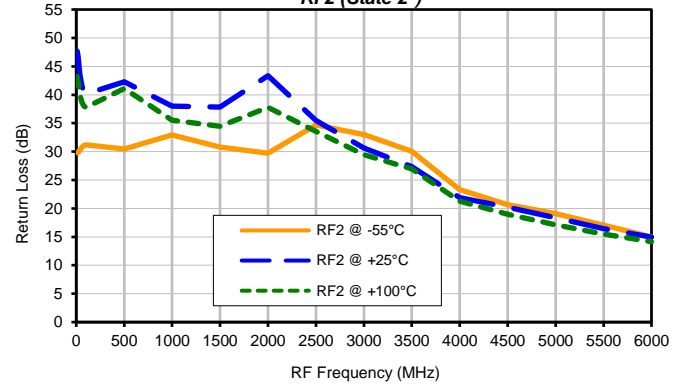
RL @ VDD=+5.25V, VEE =-5.25V over Temperature
RF1 (State 1*)



RL @ VDD=+5.25V, VEE =-5.25V over Temperature
RF2 (State 1*)



RL @ VDD=+5.25V, VEE =-5.25V over Temperature
RF2 (State 2*)



*Note:

STATE	TTL-IN	RF Com to RF1	RF Com to RF2
1	High	OFF	ON
2	Low	ON	OFF

Note: Test data of Die packaged in industry standard, 3x3mm, 12-lead MCLP package